

Description

The VST13N063 uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

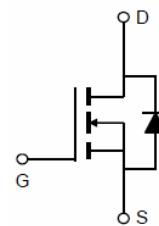
- $V_{DS} = 135V, I_D = 110A$
- $R_{DS(ON)} < 7.0m\Omega @ V_{GS}=10V$
- Excellent gate charge $\times R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification



TO-220C



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST13N063-TC	VST13N063	TO-220C	-	-	-

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	135	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	110	A
Drain Current-Continuous($T_c=100^\circ C$)	$I_D (100^\circ C)$	93	A
Pulsed Drain Current	I_{DM}	440	A
Maximum Power Dissipation	P_D	300	W
Derating factor		2	W/°C
Single pulse avalanche energy (Note 5)	E_{AS}	1296	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{θJC}	0.5	°C/W
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	135	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =135V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.5	-	4.5	V
Drain-Source On-State Resistance	R _{Ds(ON)}	V _{GS} =10V, I _D =55A	-	6.3	7.0	mΩ
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =55A	70	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C _{iss}	V _{DS} =75V, V _{GS} =0V, F=1.0MHz	-	10000	-	PF
Output Capacitance	C _{oss}		-	2046	-	PF
Reverse Transfer Capacitance	C _{rss}		-	55	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =75V, I _D =55A V _{GS} =10V, R _G =4.7Ω	-	30	-	nS
Turn-on Rise Time	t _r		-	52	-	nS
Turn-Off Delay Time	t _{d(off)}		-	69	-	nS
Turn-Off Fall Time	t _f		-	21	-	nS
Total Gate Charge	Q _g	V _{DS} =75V, I _D =55A, V _{GS} =10V	-	150	-	nC
Gate-Source Charge	Q _{gs}		-	50	-	nC
Gate-Drain Charge	Q _{gd}		-	26	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V, I _F =I _S	-		1.2	V
Diode Forward Current ^(Note 2)	I _S		-	-	110	A
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = I _S di/dt = 100A/μs ^(Note 3)	-	140	-	nS
Reverse Recovery Charge	Q _{rr}		-	498	-	nC

Notes:

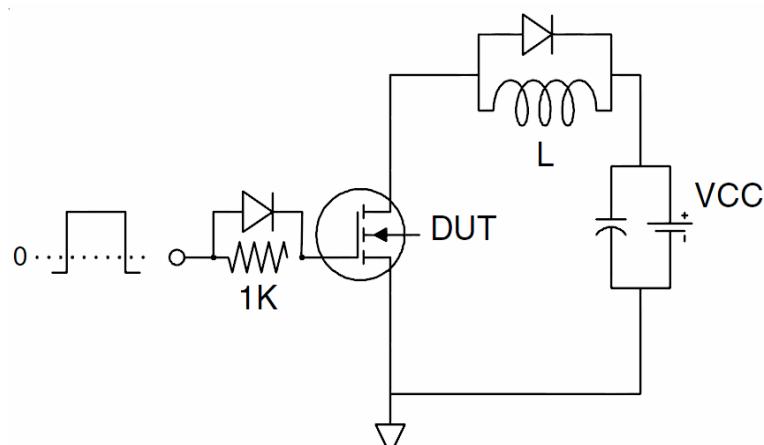
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition : T_j=25°C, V_{DD}=50V, V_G=10V, L=0.5mH, R_g=25Ω

Test Circuit

1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics

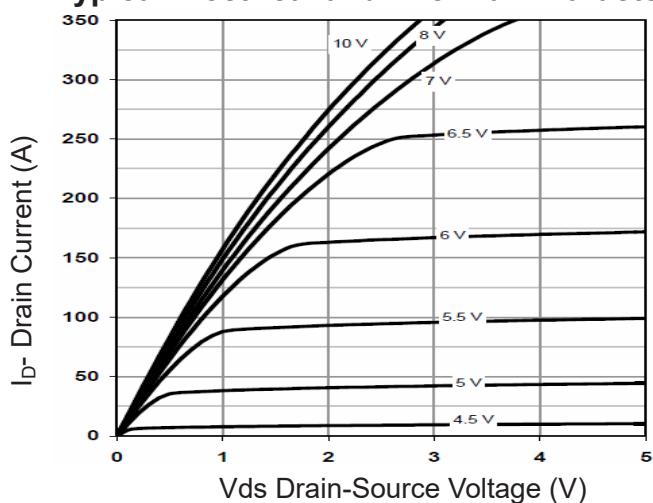


Figure 1 Output Characteristics

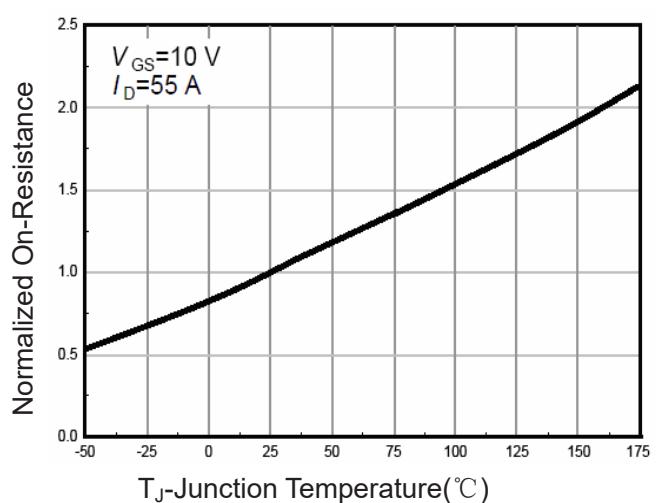


Figure 4 Rdson-JunctionTemperature

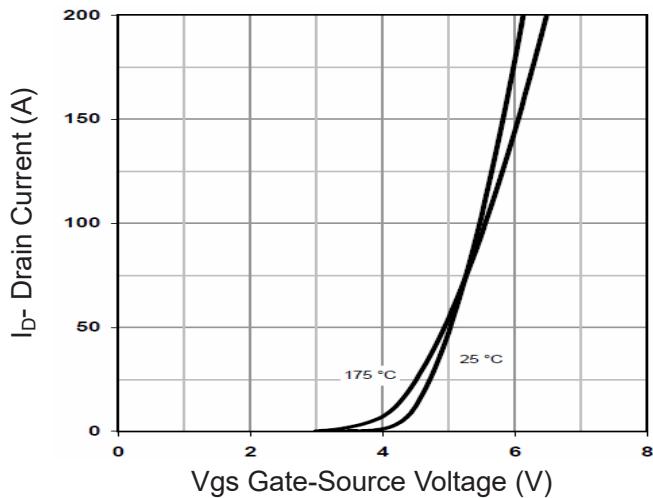


Figure 2 Transfer Characteristics

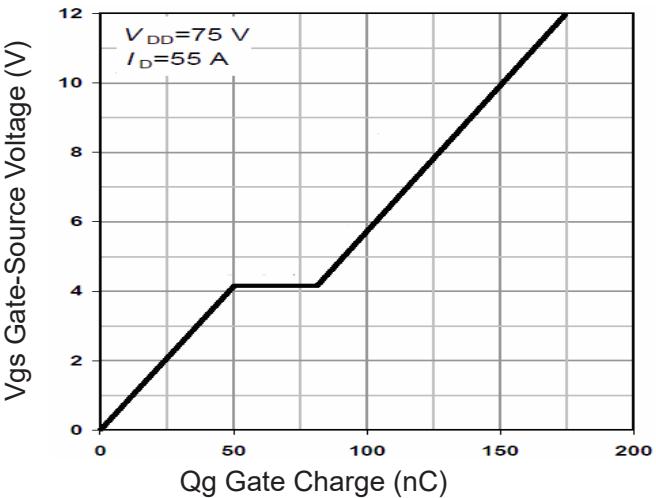


Figure 5 Gate Charge

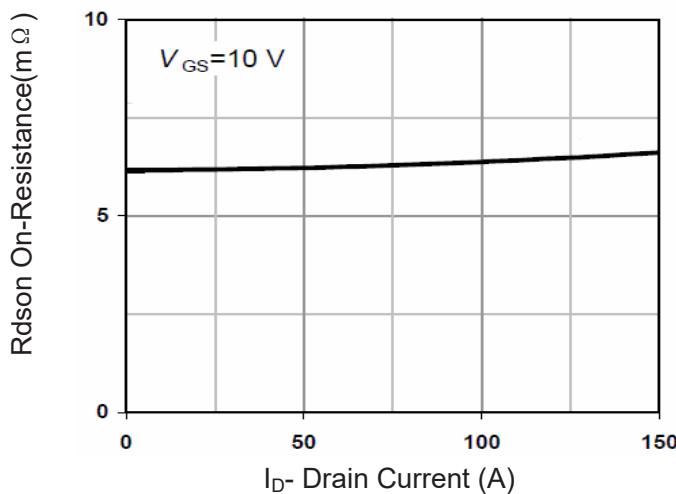


Figure 3 Rdson- Drain Current

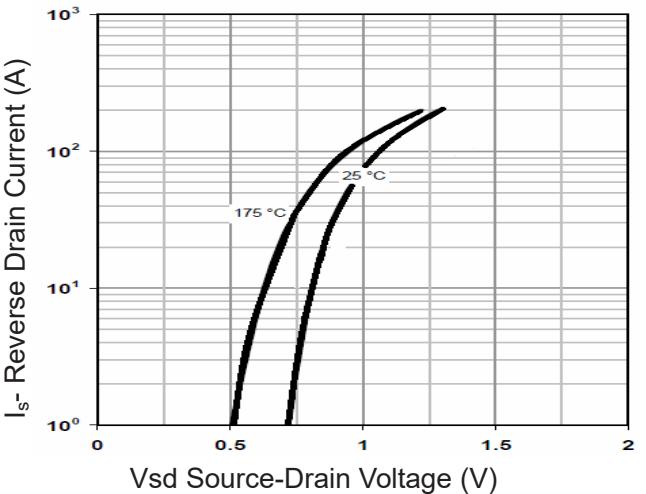
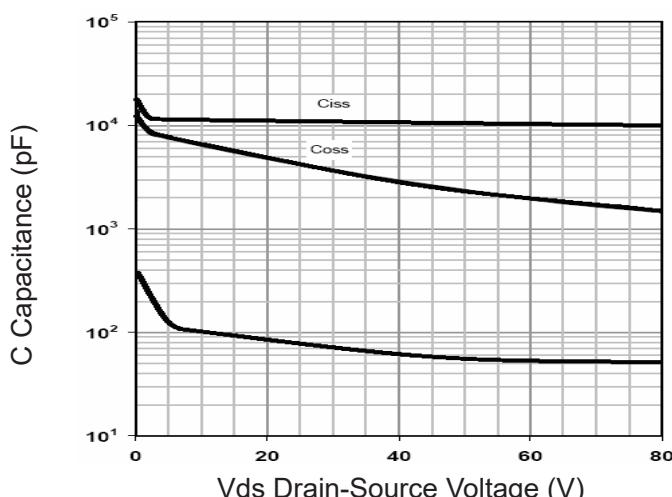
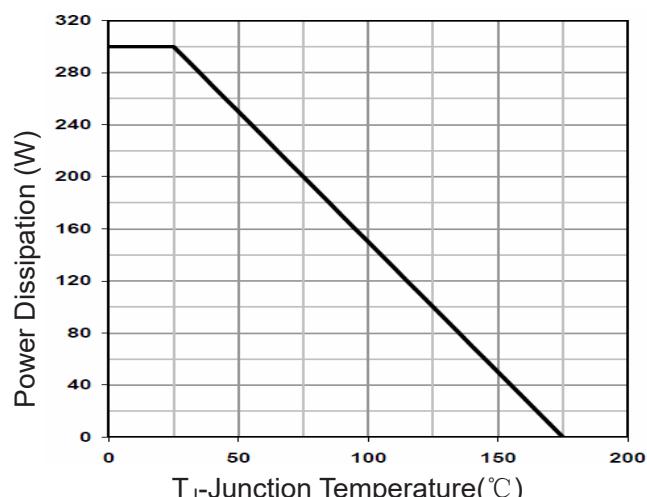
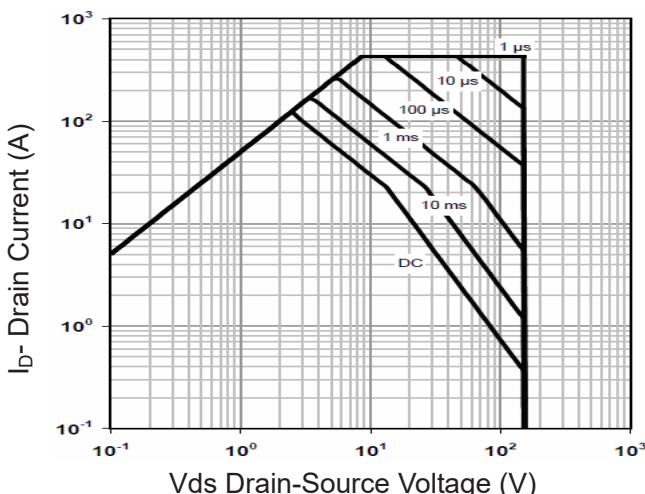
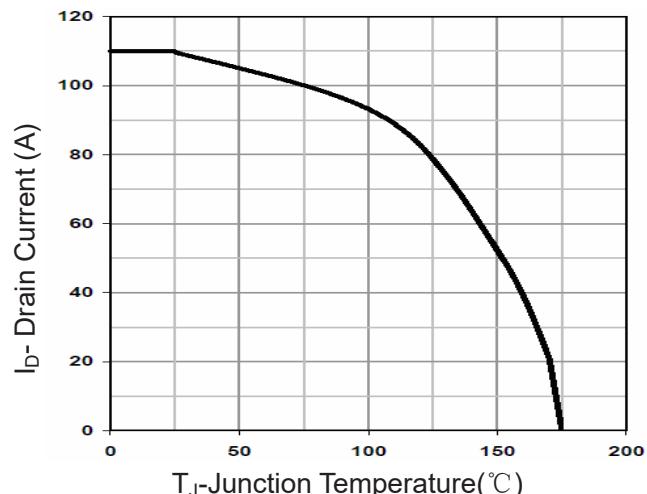
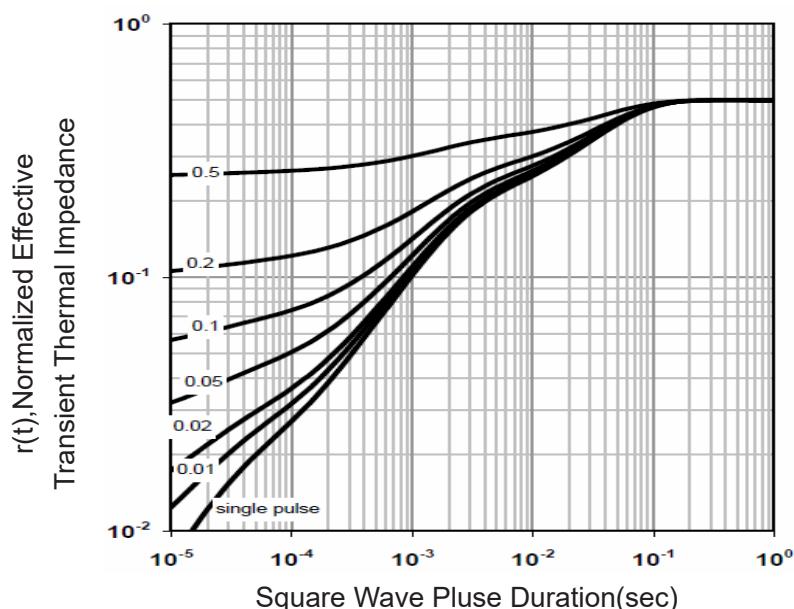


Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 Current De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance